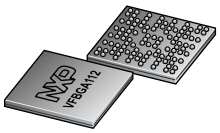
SOT2137-1

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

10 September 2024 **Package information**



1 Package summary

Package type descriptive code	VFBGA112
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-04-2023
Manufacturer package code	98ASA02081D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.85	7	7.15	mm
package width	6.85	7	7.15	mm
package height	0.74	0.86	0.98	mm
package diameter	0.29	0.38	0.39	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	112	-	

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2 Package outline

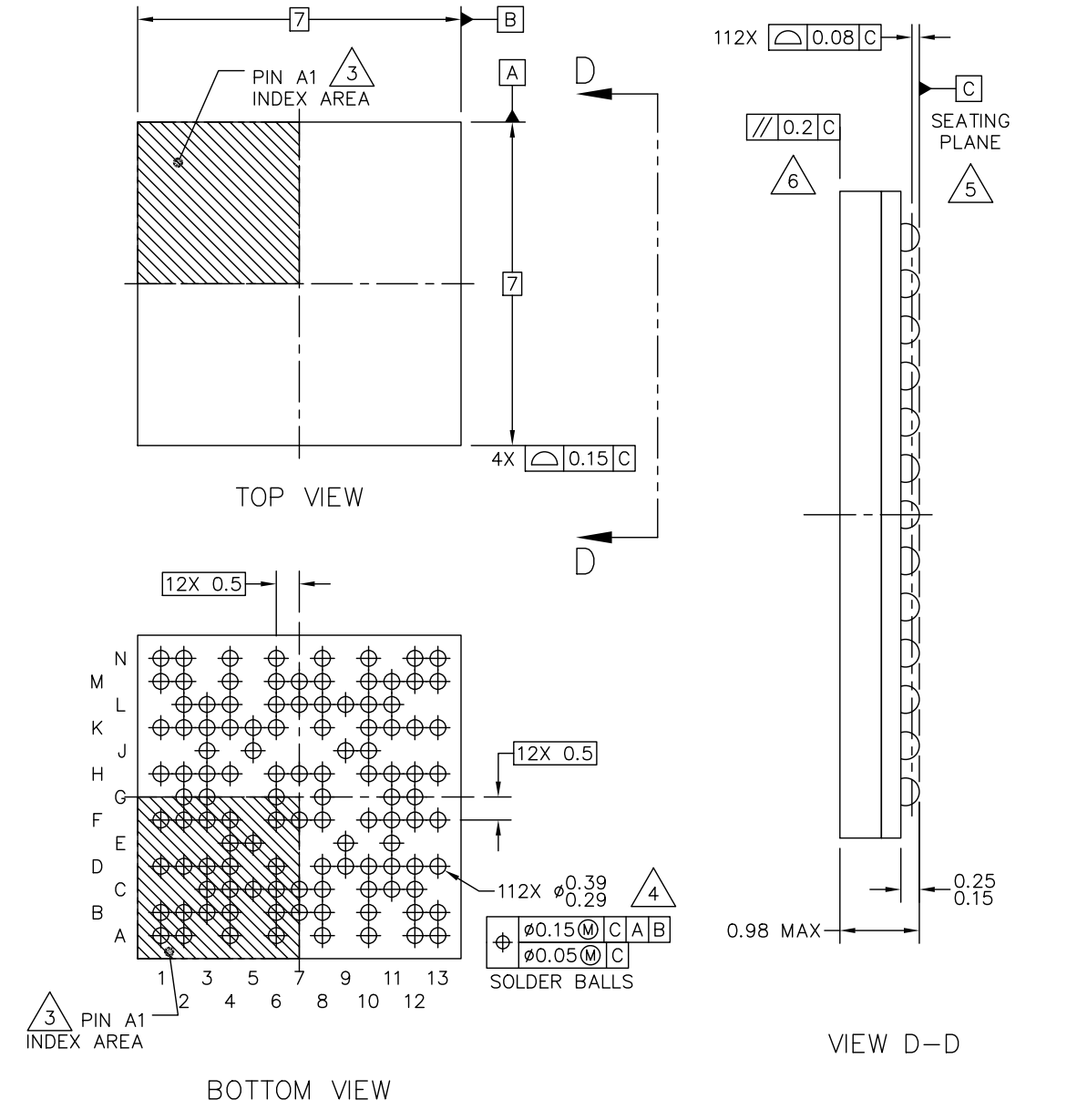

Figure 1. Package outline VFBGA112 (SOT2137-1)

3 Soldering

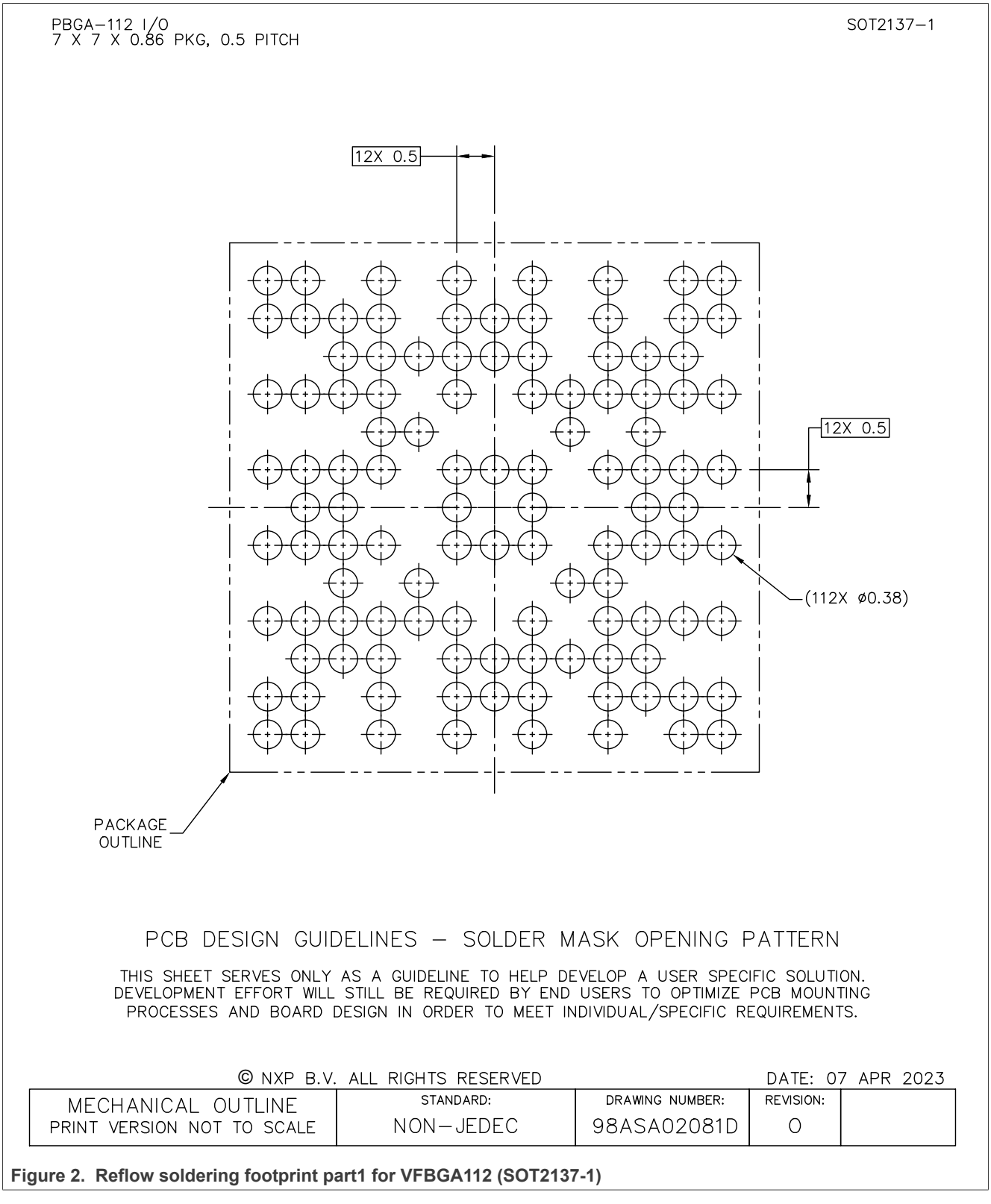

Figure 2. Reflow soldering footprint part1 for VFBGA112 (SOT2137-1)

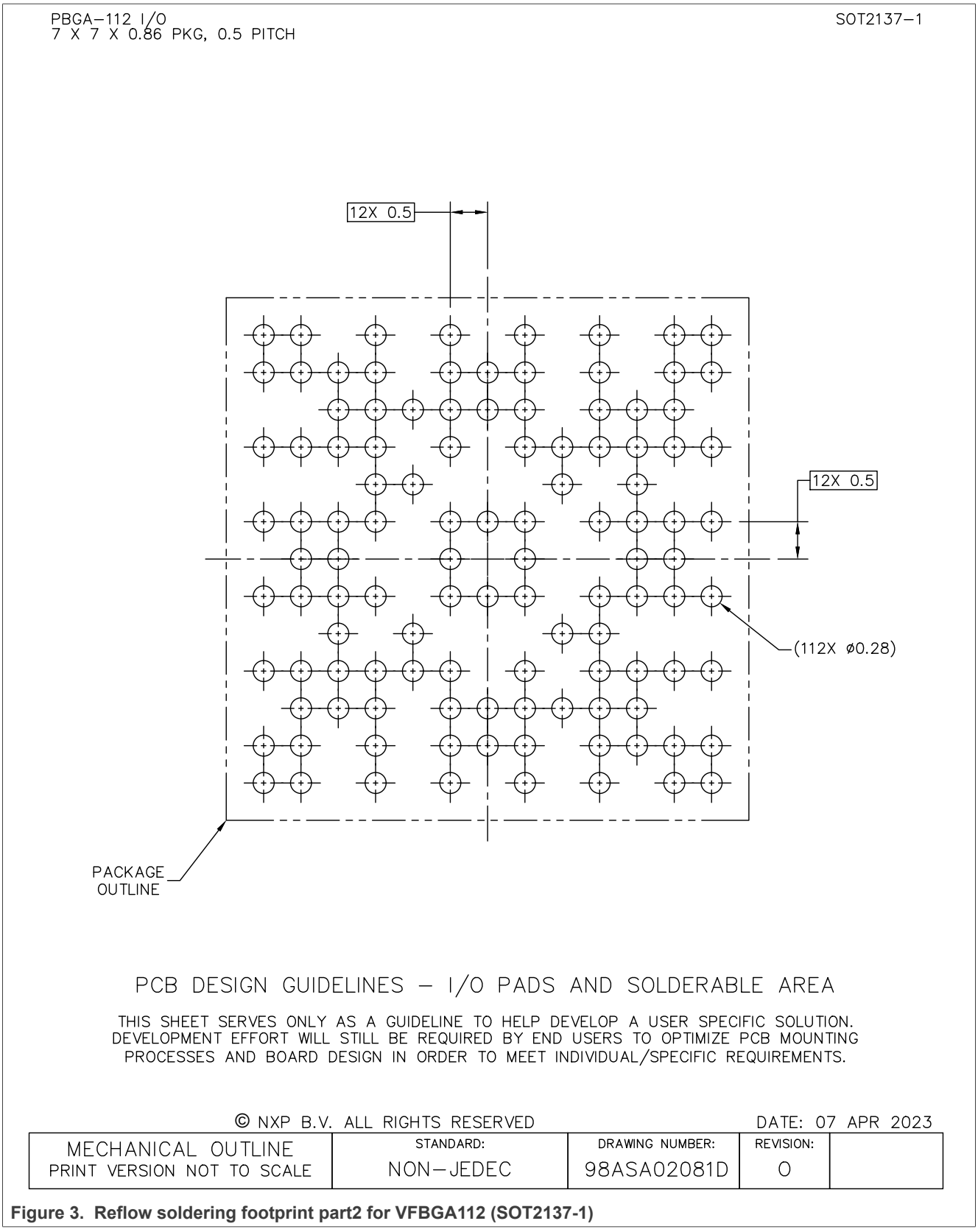

Figure 3. Reflow soldering footprint part2 for VFBGA112 (SOT2137-1)

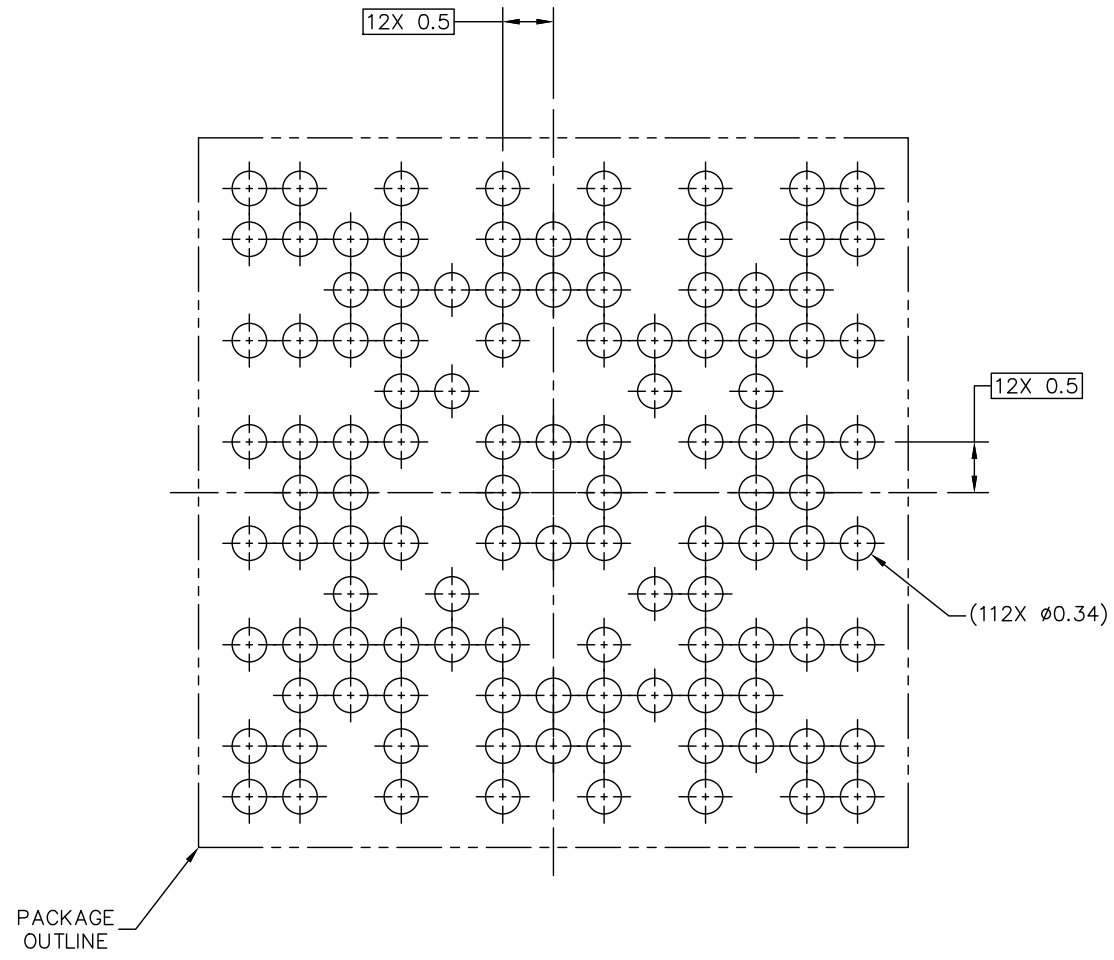

Figure 4. Reflow soldering footprint part3 for VFBGA112 (SOT2137-1)

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

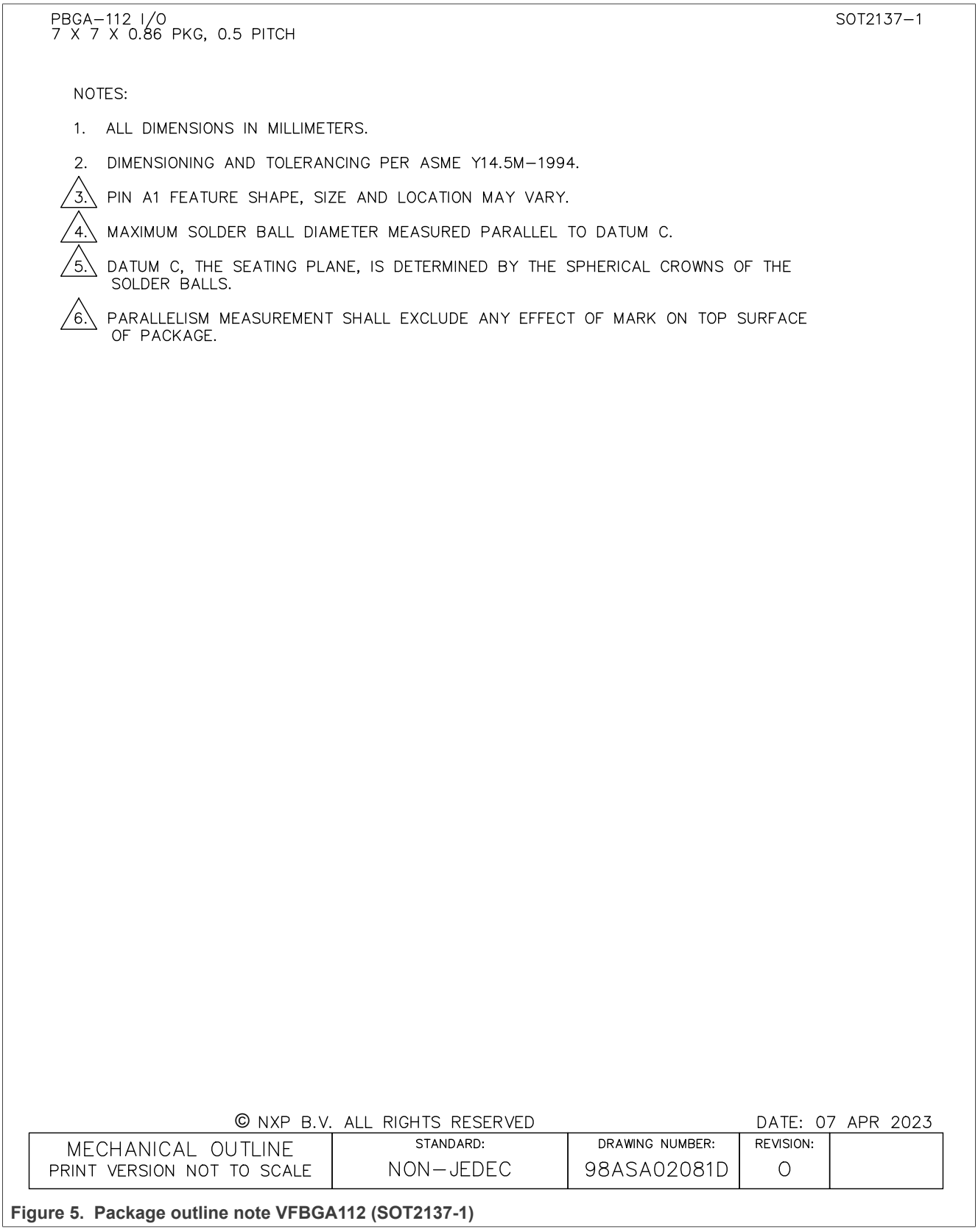

Figure 5. Package outline note VFBGA112 (SOT2137-1)

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